# 2SC5654G

#### Silicon NPN epitaxial planar type

#### For DC-DC converter

#### Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing
- Package
- Code SMini3-F2
- Marking Symbol: 2S
- Pin Name
  - 1: Base
  - 2: Emitter
- 3: Collector

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

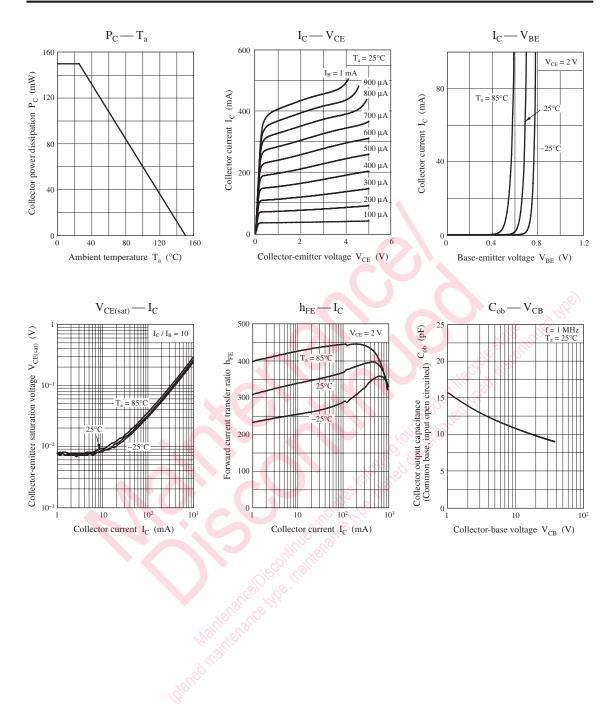
Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	20	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V	
Collector current	I <sub>C</sub>	1	A	
Peak collector current	I <sub>CP</sub>	3	А	
Collector power dissipation	P <sub>C</sub>	150	mW	
Junction temperature	Tj	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = 10 \ \mu {\rm A}, \ I_{\rm E} = 0$	20			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$	20			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	5			V
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 2 \text{ V}, \text{ I}_{C} = 100 \text{ mA}$	160		560	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = 200 \text{ mA}, I_{\rm B} = 10 \text{ mA}$		60	100	mV
Transition frequency	f <sub>T</sub>	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$		180		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		12	30	pF
(Common base, input open circuited)	Cr.					

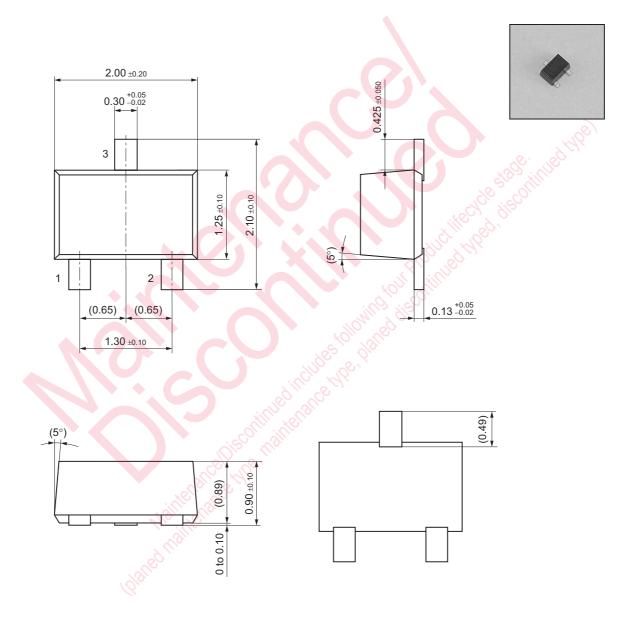
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

### Panasonic





Unit: mm



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